

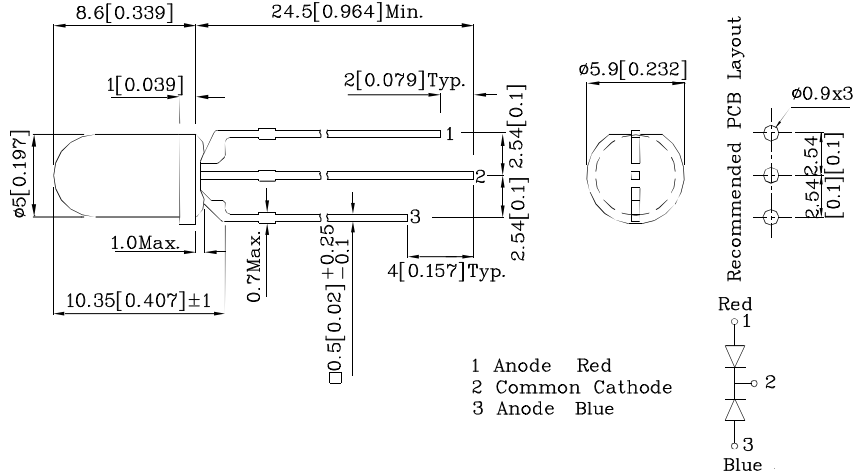
Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



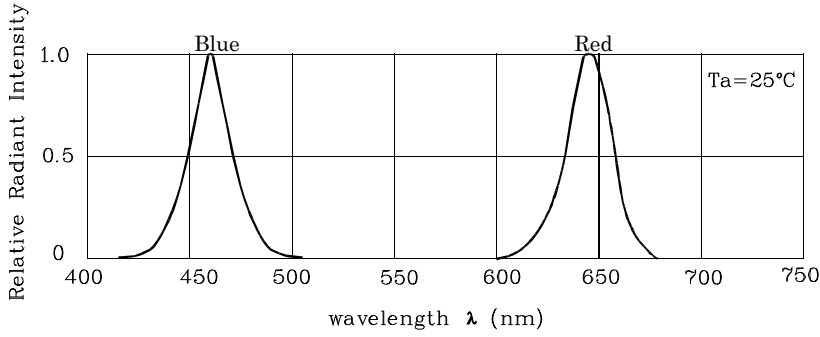
- Notes:
1. All dimensions are in millimeters (inches).
 2. Tolerance is ± 0.25 (0.01") unless otherwise noted.
 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Red (AlGaInP)	Blue (InGaIn)	Unit	Operating Characteristics (T _A =25°C)		Red (AlGaInP)	Blue (InGaIn)	Unit
Reverse Voltage	V _R	5	5	V	Forward Voltage (Typ.) (I _F =20mA)	V _F	1.95	3.3	V
Forward Current	I _F	30	30	mA	Forward Voltage (Max.) (I _F =20mA)	V _F	2.5	4	V
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	185	150	mA	Reverse Current (Max.) (V _R =5V)	I _R	10	50	uA
Power Dissipation	P _D	75	120	mW	Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λ _P	645*	460*	nm
Operating Temperature	T _A	-40 ~ +85		°C	Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λ _D	630*	465*	nm
Storage Temperature	T _{stg}	-40 ~ +85			Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	28	25	nm
Electrostatic Discharge Threshold (HBM)		3000	250	V	Capacitance (Typ.) (V _F =0V, f=1MHz)	C	35	100	pF
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds								
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds								

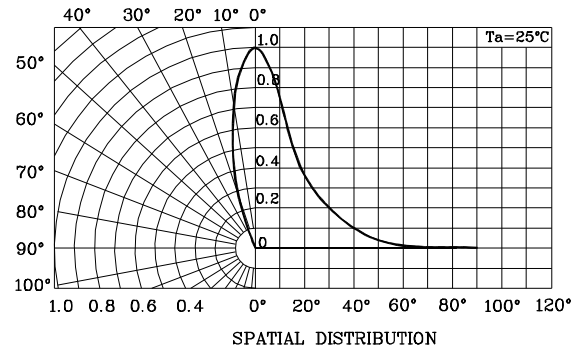
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λ _P	Viewing Angle 2θ 1/2
				min.	typ.		
XLMDKCB59M	Red	AlGaInP	White Diffused	600	1195	645*	30°
	Blue	InGaIn		80*	198*		
				200	347	460*	
				200*	347*		

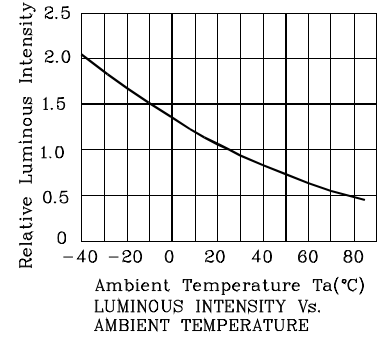
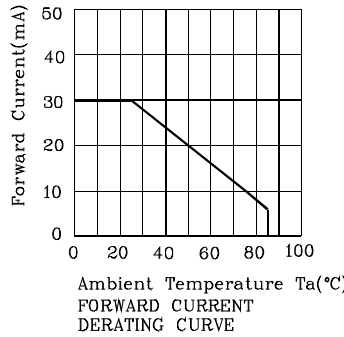
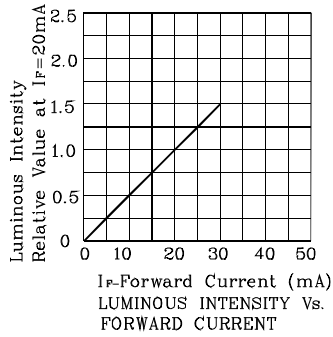
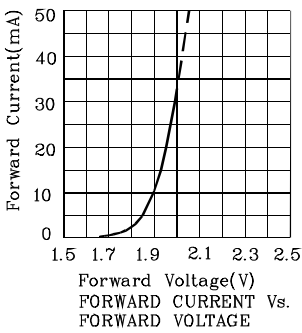
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



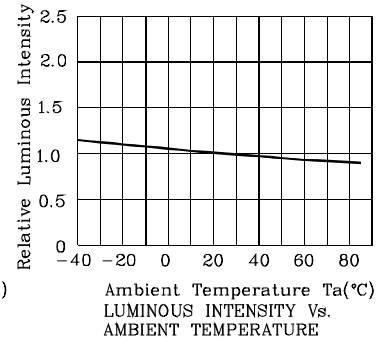
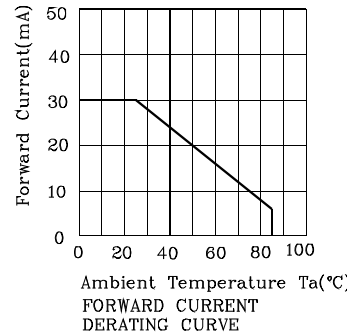
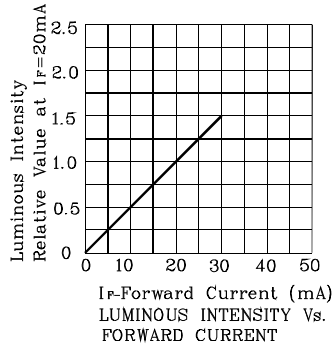
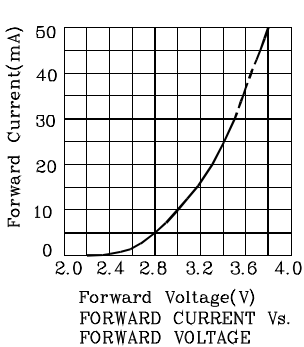
RELATIVE INTENSITY Vs. CIE WAVELENGTH



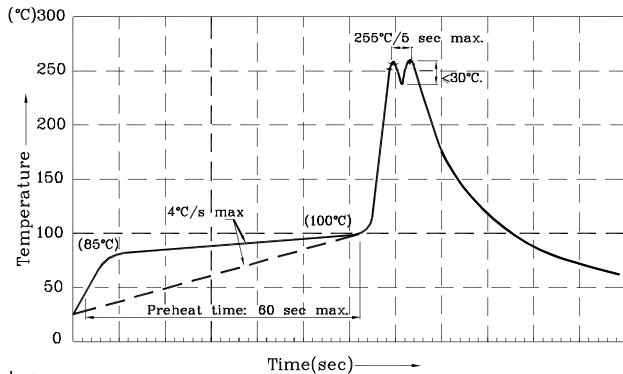
❖ Red



❖ Blue



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



- Notes:
1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
 3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
 4. Fixtures should not incur stress on the component when mounting and during soldering process.
 5. SAC 305 solder alloy is recommended.
 6. No more than one wave soldering pass.

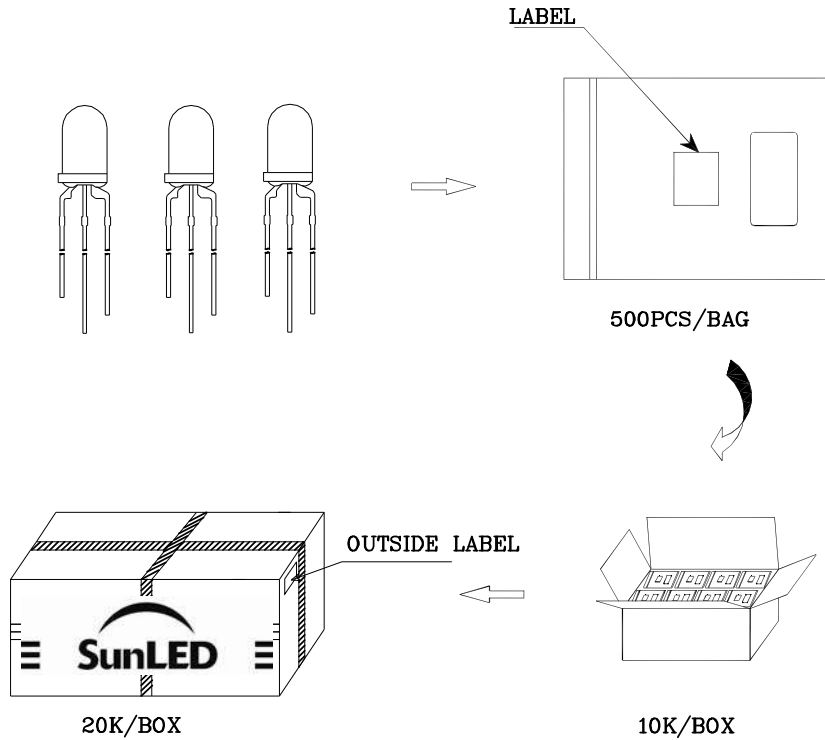
Remarks:



If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



		<table border="1"> <tr><td>Q.C</td></tr> <tr><td>Q C</td></tr> <tr><td>XX XX XXXX</td></tr> <tr><td>PASSED</td></tr> </table>	Q.C	Q C	XX XX XXXX	PASSED
Q.C						
Q C						
XX XX XXXX						
PASSED						
P/NO : XLxxx59x						
QTY : 500 pcs		CODE: XXX				
S/N : XX						
LOT NO:						
 XXXXXXXXXXXXXXXXXXXX						
RoHS Compliant						

TERMS OF USE

1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
5. The contents within this document may not be altered without prior consent by SunLED.
6. Additional technical notes are available at <http://www.SunLEDusa.com/TechnicalNotes.asp>